



Advance Product Change Notification

201510004A

Issue Date: 30-Oct-2015

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Management Summary

Change to state of the art lithography tools and introduction of advanced die protection technology.

Change Category

- | | | | |
|---|---|---|--|
| <input checked="" type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Change of AMR photolithography tool and implementation of additional wafer coating

Details of this Planned Change

1. Photolithography tool will be changed from PE mask aligner tool towards PAS stepper tool. This requires adaption of wafer layout and new mask sets. Die design will not be changed. Individual information about die coordinates in the die layout will be removed because of stepper technology. Stepper lithography is the more advanced standard technology in wafer fab processing.
2. Additional wafer coat layer as surface protection. This requires an additional mask step. Wafer coat protection is standard process in IC wafer fab manufacturing.

Why do we Plan this Change

1. Discontinuation of old photolithography technology. Stepper lithography delivers improved accuracy.
2. Robustness improvement against potential surface damages and contamination. Reduction of mechanical package stress on the die.

Identification of Affected Products

Identification by lot-ID and datecodes on labels on packages

Product Availability

Sample Information

Samples are available from 01-Feb-2016

Production

Planned first shipment 01-Sep-2016

Impact

no impact to the product's functionality anticipated.

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Self qualification: view online

Timing and Logistics

The Self Qualification Report will be ready on 30-Apr-2016.

The Final PCN is planned to be issued on: 30-Apr-2016.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 29-Nov-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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Changed Orderable Part#

KMA210:115

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